MTCON NECTIVITY

POWER SOCKET M8

INTERNAL THREAD,
SMD SOLDERING TECHNOLOGY,
THROUGH HOLE

COMMERCIAL DATA

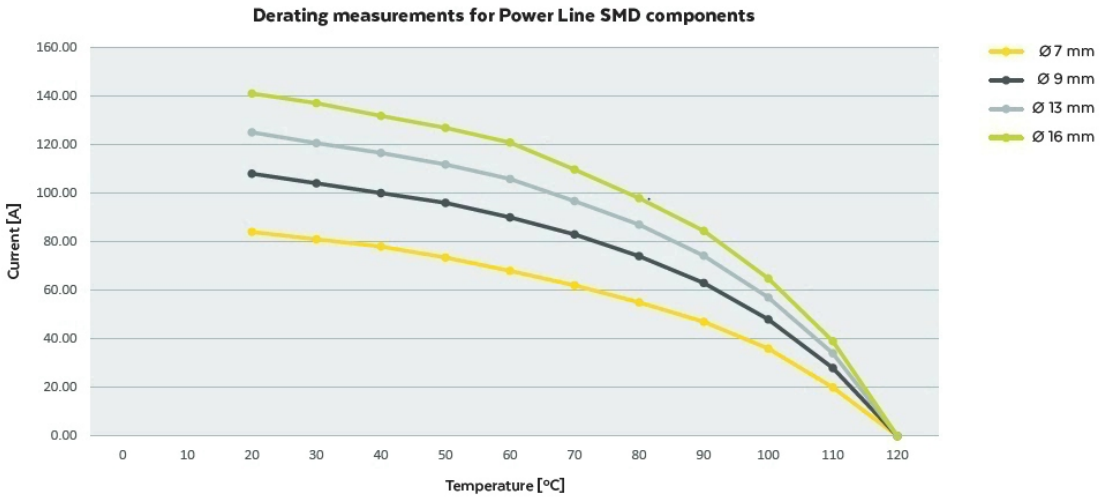
Part number	**02.6.0070**

Packing unit tape and reel - 2.6.0070.GU	**not available yet**
Customs tariff number	**85369010**
Mass	**10,55 g**
Surface	**DE (Germany)**

TECHNICAL DATA

Current carrying capacity	**ca. 180 A at 20°C / ca. 100 A at 85° C**
Material	**CuZn39Pb3**
Surface	**matt tinned**

Derating curves are snapshots under test conditions!
Testing was undertaken using two-layer circuit with 70µm copper.



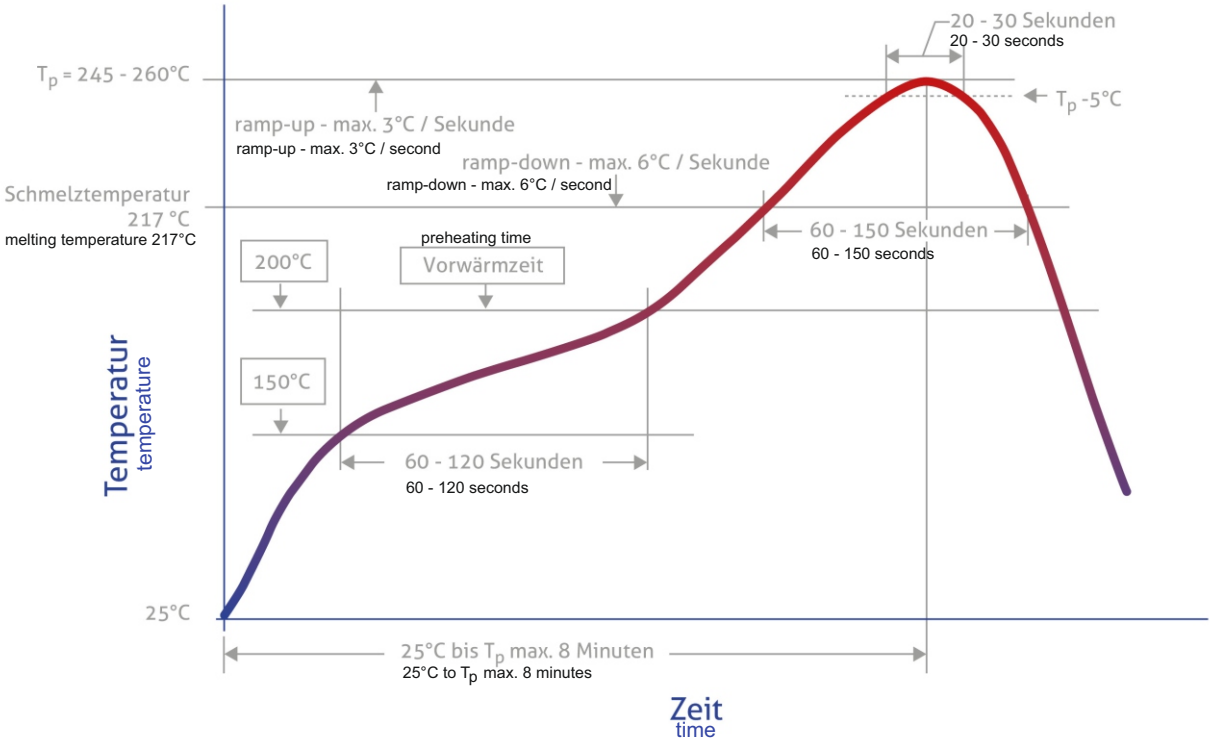
Rev. 201801

MTCON NECTIVITY

PROCESSING

Torque	**6,3 Nm**
Solder paste thickness	**150 µm**
Operating temperature	**-55°C to 150°C**

SOLDER PROFILE



Reflow Temperatur in Abhängigkeit der Leiterplattendicke:

Reflow temperature depanding on the thickness of the printed circuit board:

Eigenschaften properties	Volumen mm³ <350 volume mm³ < 350	Volumen mm³ 350-2000 volume mm³ 350-2000	Volumen mm³ >2000 volume mm³ > 2000
Leiterplattendicke (Bleifrei) < 1.6 mm PCB thickness (lead free) < 1.6 mm	260 °C	260 °C	260 °C
Leiterplattendicke (Bleifrei) 1.6 mm - 2.5 mm PCB thickness (lead free) 1.6 mm - 2.5 mm	260 °C	250 °C	245 °C
Leiterplattendicke (Bleifrei) ≥ 2.5 mm PCB thickness (lead free) ≥ 2.5 mm	250 °C	245 °C	245 °C

mit Bezug auf IPC/JEDEC J-STD-020D
regarding IPC/JEDEC J-STD-020D

CONFORMITY

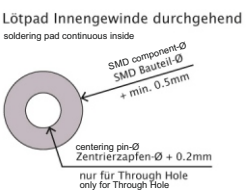
- RoHS compliant

RoHS COMPLIANT

TAPE AND REEL

not available yet

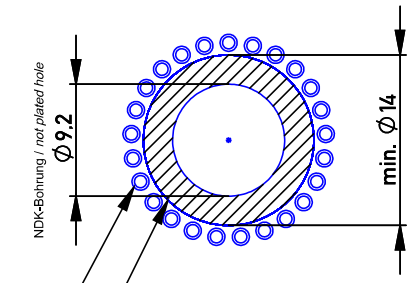
LAYOUT



MTCONNECTIVITY

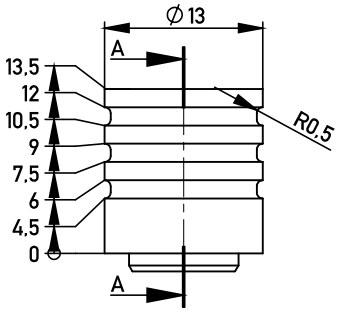
LAYOUT

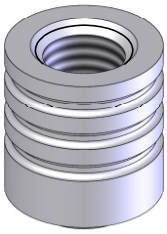
Verpackung / *packaging*	Artikelnummer / *part number*
lose / *bulk*	02.6.0070
tape and reel	not available

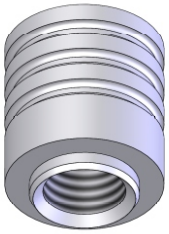


Empfehlung Lötpad / *recommendation solder pad*
vollflächiges Pad min. 0.5mm umlaufend größer als Element /
full-face pad all round min. 0.5mm bigger than the element

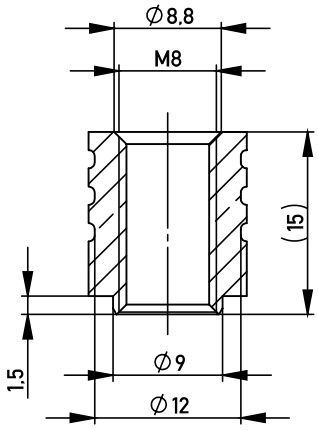
optionale DK-Bohrungen umlaufend um das Pad - für höhere Stromtragfähigkeit /
optional plated holes around the pad - for higher current ratings







cut A-A
SCHNITT A-A



RoHS COMPLIANT

Ausführung: SMD
Max. Drehmoment: 6,3 Nm
Gewicht: 10,55 g
Technische Änderungen vorbehalten

execution: SMD
max. torque: 6,3 Nm
weight: 10.55 g
technical subject to change

Werkstoff / *material*	CuZn39Pb3	Toleranz / *tolerance*	Maßstab / *scale* 2:1
Oberfläche / *surface plating*	matt verzinnt / *mat tin-plated*	DIN ISO 2768-mH	Zeichnungsnummer / *drawing number* 02.6.0070
Prozessbedingte Fehlstellen in Galvanik möglich! *imperfections during electro plating process possible!*		all dimensions in mm	

	Datum / *date*	Name / *name*
Bearb. / *drawer*	27.02.2017	
gepr. / *auth.*		
geän. / *mod.*		

Benennung / description

Power Socket M8
SMD, 13er rund, through hole
SMD, thirteens round, through hole

Index	Änderung / *modification*	Datum / *date*	Name / *name*
	REACH entfernen	17.07.2018	
A	Neuerstellung	27.02.2017	

MTCONNECTIVITY
power2pcb GmbH
Hauptstraße 18
74676 Niedernhall
GERMANY

Vertraulich! Alle Rechte vorbehalten. Weitergabe oder Vervielfältigung ohne vorherige schriftliche Zustimmung verboten.
Confidential! All rights reserved. Forwarding or duplication without previous written permission prohibited.

K
A4

Rev. 201801